



General Description

The MAX5889 advanced 12-bit, 600Msps, digital-toanalog converter (DAC) meets the demanding performance requirements of signal synthesis applications found in wireless base stations and other communications applications. Operating from 3.3V and 1.8V supplies, the MAX5889 DAC supports update rates of 600Msps using high-speed LVDS inputs while consuming only 292mW of power and offers exceptional dynamic performance such as 79dBc spurious-free dynamic range (SFDR) at f_{OUT} = 30MHz.

The MAX5889 utilizes a current-steering architecture that supports a 2mA to 20mA full-scale output current range, and produces -2dBm to -22dBm full-scale output signal levels with a double-terminated 50Ω load. The MAX5889 features an integrated 1.2V bandgap reference and control amplifier to ensure high-accuracy and low-noise performance. A separate reference input (REFIO) allows for the use of an external reference source for optimum flexibility and improved gain accuracy.

The MAX5889 digital inputs accept LVDS voltage levels, and the flexible clock input can be driven differentially or single-ended, AC- or DC-coupled. The MAX5889 is available in a 68-pin QFN package with an exposed paddle (EP) and is specified for the extended (-40°C to +85°C) temperature range.

Refer to the MAX5891 and MAX5890 data sheets for pincompatible 16-bit and 14-bit versions of the MAX5889.

Applications

Base Stations: Single-Carrier UMTS, CDMA, GSM

Communications: Fixed Broadband Wireless Access, Point-to-Point Microwave

Direct Digital Synthesis (DDS)

Cable Modem Termination Systems (CMTS)

Automated Test Equipment (ATE)

Instrumentation

PART	RESOLUTION (BITS)	UPDATE RATE (Msps)	LOGIC INPUT
MAX5889	12	600	LVDS
MAX5890	14	600	LVDS
MAX5891	16	600	LVDS

Selector Guide

_Features

- ♦ 600Msps Output Update Rate
- Low-Noise Spectral Density: -157dBFS/Hz at four = 36MHz
- Excellent SFDR and IMD Performance SFDR = 79dBc at fOUT = 30MHz (to Nyquist) SFDR = 67dBc at fOUT = 130MHz (to Nyquist) IMD = -95dBc at fOUT = 30MHz IMD = -70dBc at fOUT = 130MHz
- ◆ ACLR = 72dB at four = 122.88MHz
- ♦ 2mA to 20mA Full-Scale Output Current
- LVDS-Compatible Digital Inputs
- On-Chip 1.2V Bandgap Reference
- Low 292mW Power Dissipation at 600Msps
- Compact (10mm x 10mm) QFN-EP Package
- Evaluation Kit Available (MAX5891EVKIT)

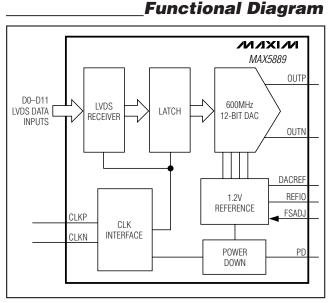
_Ordering Information

PART	TEMP RANGE	PIN- PACKAGE	PKG CODE
MAX5889EGK-D	-40°C to +85°C	68 QFN-EP*	G6800-4
MAX5889EGK+D	-40°C to +85°C	68 QFN-EP*	G6800-4

*EP = Exposed paddle.

D = Dry pack.

+Denotes lead-free package.



Pin Configuration appears at end of data sheet.

___ Maxim Integrated Products 1

For pricing, delivery, and ordering information, please contact Maxim/Dallas Direct! at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

MAX5889

ABSOLUTE MAXIMUM RATINGS

AVDD1.8, DVDD1.8 to AGND, DGND, DACREF,

AVDD1.8, DVDD1.8 10 AGIND, DGIND, DACREF,	
and CGND0.3V to +2.16V	
AV _{DD3.3} , DV _{DD3.3} , AV _{CLK} to AGND, DGND,	
DACREF, and CGND0.3V to +3.9V	
REFIO, FSADJ to AGND, DACREF,	
DGND, and CGND0.3V to (AV _{DD3.3} + 0.3V)	
OUTP, OUTN to AGND, DGND, DACREF,	
and CGND1.2V to (AV _{DD3.3} + 0.3V)	
CLKP, CLKN to AGND, DGND, DACREF,	
and CGND0.3V to (AV _{CLK} + 0.3V)	
PD to AGND, DGND, DACREF,	

and CGND.....-0.3V to (DV_{DD3.3} + 0.3V)

Digital Data Inputs (D0N–D11N, D0P–D11P) to AGND, DGND, DACREF, and CGND-0.3V to (DV_{DD1.8} + 0.3V)

Continuous Power Dissipation ($T_A = +70^{\circ}$ C) (Note 1)

68-Pin QFN-EP (derate 28.6mW/°	C above +70°C)3333mW
Thermal Resistance θ_{JA} (Note 1)	24°C/W
Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	60°C to +150°C
Lead Temperature (soldering, 10s)	+300°C

Note 1: Thermal resistance based on a multilayer board with 4 x 4 via array in exposed paddle area.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(AV_{DD3.3} = DV_{DD3.3} = AV_{CLK} = 3.3V, AV_{DD1.8} = DV_{DD1.8} = 1.8V$, external reference $V_{REFIO} = 1.2V$, output load 50 Ω double-terminated, transformer-coupled output, $I_{OUT} = 20mA$, $T_A = -40^{\circ}C$ to $+85^{\circ}C$, unless otherwise noted. Specifications at $T_A \ge +25^{\circ}C$ are guaranteed by production testing. Specifications at $T_A < +25^{\circ}C$ are guaranteed by design and characterization. Typical values are at $T_A = +25^{\circ}C$.)

PARAMETER	SYMBOL	CO	NDITIONS	MIN	ТҮР	MAX	UNITS	
STATIC PERFORMANCE	•	·						
Resolution					12		Bits	
Integral Nonlinearity	INL	Measured differen	tially		±0.25		LSB	
Differential Nonlinearity	DNL	Measured differen	tially		±0.15		LSB	
Offset Error	OS			-0.02	0.001	+0.02	%FS	
Full-Scale Gain Error	GE _{FS}	External reference		-4	±1	+4	%FS	
Coin Drift Tompoo		Internal reference			±130		nnm/°C	
Gain-Drift Tempco		External reference			±100		ppm/°C	
Full-Scale Output Current	Iout			2		20	mA	
Output Compliance		Single-ended	Single-ended			+1.1	V	
Output Resistance	Rout				1		MΩ	
Output Capacitance	COUT				5		рF	
Output Leakage Current		PD = high, power-	down mode		±1		μA	
DYNAMIC PERFORMANCE								
Maximum DAC Update Rate				600			Msps	
Minimum DAC Update Rate					1		Msps	
		f _{CLK} = 500MHz, -12dBFS, 20MHz	f _{OUT} = 36MHz, AFULL-SCALE = -3.5dBm		-157			
Noise Spectral Density	N	offset from the carrier	f _{OUT} = 151MHz, AFULL-SCALE = -6.4dBm	-152			– dBFS/Hz	

ELECTRICAL CHARACTERISTICS (continued)

 $(AV_{DD3.3} = DV_{DD3.3} = AV_{CLK} = 3.3V, AV_{DD1.8} = DV_{DD1.8} = 1.8V$, external reference $V_{REFIO} = 1.2V$, output load 50 Ω double-terminated, transformer-coupled output, $I_{OUT} = 20mA$, $T_A = -40^{\circ}C$ to $+85^{\circ}C$, unless otherwise noted. Specifications at $T_A \ge +25^{\circ}C$ are guaranteed by production testing. Specifications at $T_A < +25^{\circ}C$ are guaranteed by design and characterization. Typical values are at $T_A = +25^{\circ}C$.

PARAMETER	SYMBOL	CONDITIONS		MIN	ТҮР	MAX	UNITS
		f _{CLK} = 200MHz,	fout = 16MHz		88		
		0dBFS	fout = 30MHz		85		
		f _{CLK} = 200MHz,	fout = 16MHz		78		1
Spurious-Free		-12dBFS	fout = 30MHz		77		-10 -
Dynamic Range to Nyquist	SFDR		fout = 16MHz	76	81		dBc
, and the second s		$f_{CLK} = 500 MHz,$	fout = 30MHz		80		
		0dBFS	fout = 130MHz		71		
			f _{OUT} = 200MHz		54		
	TTIMD	f _{CLK} = 500MHz	$f_{OUT1} = 29MHz,$ $f_{OUT2} = 30MHz,$ -6.5dBFS per tone		-95		dDa
Two-Tone IMD	TTIMD	f _{CLK} = 500MHz	$f_{OUT1} = 129MHz,$ $f_{OUT2} = 130MHz,$ -6.5dBFS per tone		-70		dBc
		WCDMA single carrier	f _{CLK} = 491.52MHz, f _{OUT} = 30.72MHz		80		
Adjacent Channel	ACLR		f _{CLK} = 491.52MHz, f _{OUT} = 122.88MHz		72		- dB
Leakage Power Ratio		n WCDMA four carriers	f _{CLK} = 491.52MHz, f _{OUT} = 30.72MHz		72	UB	
			f _{CLK} = 491.52MHz, f _{OUT} = 122.88MHz		67		
Output Bandwidth	BW-1dB	(Note 2)			1000		MHz
EFERENCE							
Internal Reference Voltage Range	VREFIO			1.14	1.2	1.26	V
Reference Input Voltage Range	VREFIOCR	Using external reference	се	0.10	1.2	1.32	V
Reference Input Resistance	R _{REFIO}				10		kΩ
Reference Voltage Temperature Drift	TCOREF				±30		ppm/°C
ANALOG OUTPUT TIMING (Figur	e 3)						
Output Fall Time	tFALL	90% to 10% (Note 3)			0.4		ns
Output Rise Time	tRISE	10% to 90% (Note 3)			0.4		ns
Output Propagation Delay	tPD	Reference to data later	ncy (Note 3)		2.5		ns
Output Settling Time		To 0.025% of the final			11		ns

ELECTRICAL CHARACTERISTICS (continued)

 $(AV_{DD3.3} = DV_{DD3.3} = AV_{CLK} = 3.3V, AV_{DD1.8} = DV_{DD1.8} = 1.8V$, external reference $V_{REFIO} = 1.2V$, output load 50 Ω double-terminated, transformer-coupled output, $I_{OUT} = 20mA$, $T_A = -40^{\circ}C$ to $+85^{\circ}C$, unless otherwise noted. Specifications at $T_A \ge +25^{\circ}C$ are guaranteed by production testing. Specifications at $T_A < +25^{\circ}C$ are guaranteed by design and characterization. Typical values are at $T_A = +25^{\circ}C$.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
Glitch Impulse		Measured differentially		1		pV•s
Output Nicion	Neur	I _{OUT} = 2mA		30		m A // []=
Output Noise	Nout	I _{OUT} = 20mA		30		pA/√Hz
TIMING CHARACTERISTICS						
Input Data Rate					600	MWps
Data Latency				5.5		Clock cycles
Data to Clock Setup Time	t SETUP	Referenced to rising edge of clock (Note 4)	-1.5			ns
Data to Clock Hold Time	thold	Referenced to rising edge of clock (Note 4)	2.6			ns
Clock Frequency	fCLK	CLKP, CLKN			600	MHz
Minimum Clock Pulse-Width High	tсн	CLKP, CLKN		0.6		ns
Minimum Clock Pulse-Width Low	tCL	CLKP, CLKN		0.6		ns
Turn-On Time	t SHDN	External reference, PD falling edge to output settle within 1%		350		μs
CMOS LOGIC INPUT (PD)			1			
Input Logic High	VIH		0.7 x DV _{DD3.3}			V
Input Logic Low	VIL				0.3 x DV _{DD3.3}	V
Input Current	lin		-10	±1.8	+10	μA
Input Capacitance	CIN			3		pF
LVDS INPUTS		•				•
Differential Input High	VIHLVDS	(Notes 6, 7, 8)	+100		+1000	mV
Differential Input Low	VILLVDS	(Notes 6, 7, 8)	-1000		-100	mV
Internal Common-Mode Bias	VICMLVDS		1.125		1.375	V
Differential Input Resistance	RIDLVDS			110		Ω
Common-Mode Input Resistance	RICMLVDS			3.2		kΩ
Input Capacitance	CINLVDS			3		pF
DIFFERENTIAL CLOCK INPUTS (CLKP, CLKN	۱)				
Clock Common-Mode Voltage		CLKP and CLKN are internally biased	A	AVCLK /	2	V
Minimum Differential Input Voltage Swing				0.5		Vp-p
Minimum Common-Mode Voltage				1		V
Maximum Common-Mode Voltage				1.9		V

ELECTRICAL CHARACTERISTICS (continued)

 $(AV_{DD3.3} = DV_{DD3.3} = AV_{CLK} = 3.3V, AV_{DD1.8} = DV_{DD1.8} = 1.8V$, external reference $V_{REFIO} = 1.2V$, output load 50 Ω double-terminated, transformer-coupled output, $I_{OUT} = 20$ mA, $T_A = -40^{\circ}$ C to $+85^{\circ}$ C, unless otherwise noted. Specifications at $T_A \ge +25^{\circ}$ C are guaranteed by production testing. Specifications at $T_A < +25^{\circ}$ C are guaranteed by design and characterization. Typical values are at $T_A = +25^{\circ}$ C.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input Resistance	RCLK	Single-ended		5		kΩ
Input Capacitance	CCLK			3		рF
POWER SUPPLIES						
Apolog Supply Voltage Dange	AV _{DD3.3}		3.135	3.3	3.465	V
Analog Supply Voltage Range	AV _{DD1.8}		1.710	1.8	1.890	V
Clock Supply Voltage Range	AVCLK		3.135	3.3	3.465	V
Disital Currely Valtage Denge	DV _{DD3.3}		3.135	3.3	3.465	V
Digital Supply Voltage Range	DV _{DD1.8}		1.710	1.8	1.890	V
		$f_{CLK} = 100MHz, f_{OUT} = 16MHz$		26.5		
	IAVDD3.3	$f_{CLK} = 500MHz, f_{OUT} = 16MHz$		26.5	28.5	mA
Analog Supply Current		$f_{CLK} = 600MHz, f_{OUT} = 16MHz$		26.5		
		$f_{CLK} = 100MHz, f_{OUT} = 16MHz$		11.3		
	IAVDD1.8	$f_{CLK} = 500MHz, f_{OUT} = 16MHz$		50	58	
		$f_{CLK} = 600MHz, f_{OUT} = 16MHz$		60		
Clock Supply Current		$f_{CLK} = 100MHz, f_{OUT} = 16MHz$		2.8		
	IAVCLK	$f_{CLK} = 500MHz, f_{OUT} = 16MHz$		2.8	3.6	mA
		$f_{CLK} = 600MHz, f_{OUT} = 16MHz$		2.8		
		$f_{CLK} = 100MHz, f_{OUT} = 16MHz$		0.2		
	IDVDD3.3	$f_{CLK} = 500MHz, f_{OUT} = 16MHz$		0.2	0.5	
		$f_{CLK} = 600MHz, f_{OUT} = 16MHz$		0.2		
Digital Supply Current		$f_{CLK} = 100MHz, f_{OUT} = 16MHz$		10.2		mA
	IDVDD1.8	$f_{CLK} = 500MHz, f_{OUT} = 16MHz$		42	48	
		$f_{CLK} = 600MHz, f_{OUT} = 16MHz$		48		
		$f_{CLK} = 100MHz, f_{OUT} = 16MHz$		137		
		$f_{CLK} = 500MHz, f_{OUT} = 16MHz$		263	297	mW
Total Power Dissipation	PDISS	$f_{CLK} = 600MHz, f_{OUT} = 16MHz$		292		
		Power-down, clock static low, data input static		13		μW
Power-Supply Rejection Ratio	PSRR	(Note 5)		±0.025		%FS

Note 2: This parameter does not include update-rate-dependent effects of sin(x)/x filtering inherent in the MAX5889.

Note 3: Parameter measured single-ended with 50Ω double-terminated outputs.

Note 4: Not production tested. Guaranteed by design.

Note 5: Parameter defined as the change in midscale output caused by a ±5% variation in the nominal supply voltages.

Note 6: Not production tested. Guaranteed by design.

Note 7: Differential input voltage defined as $V_{D_P} - V_{D_N}$.



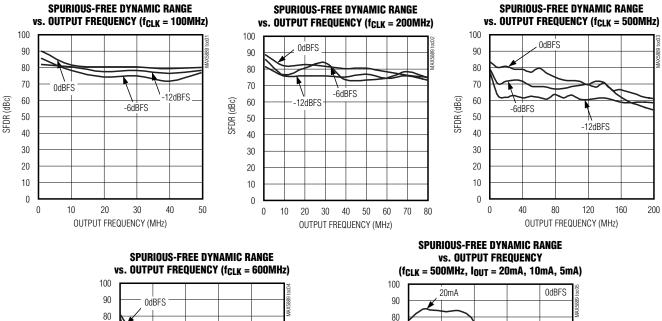
Note 8: Combination of logic-high/-low and common-mode voltages must not exceed absolute maximum rating for D_P/D_N inputs.



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Typical Operating Characteristics

 $(AV_{DD3.3} = DV_{DD3.3} = AV_{CLK} = 3.3V, AV_{DD1.8} = DV_{DD1.8} = 1.8V$, external reference $V_{REFIO} = 1.2V$, output load 50 Ω double-terminated, transformer-coupled output, $I_{OUT} = 20$ mA, $T_A = +25^{\circ}$ C, unless otherwise noted.)



70

60

50

40

30

20

10

0

0

10mA

40

80

OUTPUT FREQUENCY (MHz)

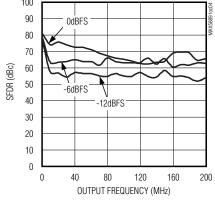
5mA

120

160

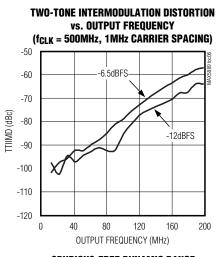
200

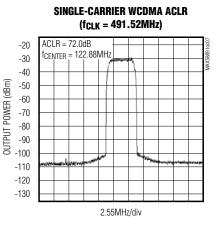
SFDR (dBc)

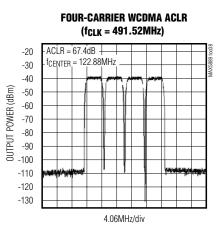


Typical Operating Characteristics (continued)

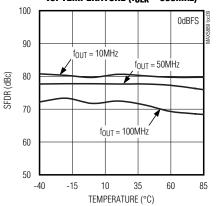
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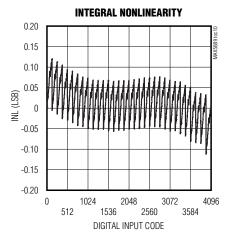


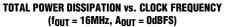


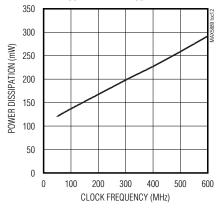


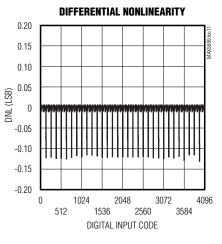
SPURIOUS-FREE DYNAMIC RANGE vs. TEMPERATURE (f_{CLK} = 500MHz)











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MAX5889

MAX5889

PIN	NAME	FUNCTION
1, 46, 48, 50, 52, 54, 56, 58, 60, 63, 65, 67	D0N, D11N, D10N, D9N, D8N, D7N, D6N, D5N, D4N, D3N, D2N, D1N	Differential Negative LVDS Inputs. Data bits D0–D11 (offset binary format).
2–9	N.C.	No Connection. Leave floating or connect to DGND.
10	DGND	Digital Ground. Ground return for DV _{DD3.3} and DV _{DD1.8} .
11	DV _{DD3.3}	Digital Supply Voltage. Accepts a 3.135V to 3.465V supply voltage range. Bypass with a 0.1µF capacitor to DGND.
12	PD	Power-Down Input. Set PD high to force the DAC into power-down mode. Set PD low for normal operation. PD has an internal $2\mu A$ pulldown.
13, 42, 43, 44	N.C.	No Connection. Leave floating or connect to AGND.
14, 21, 22, 25, 26, 31, 32	AV _{DD3.3}	Analog Supply Voltage. Accepts a 3.135V to 3.465V supply voltage range. Bypass with a 0.1 μ F capacitor to AGND.
15, 20, 23, 24, 27, 30, 33	AGND	Analog Ground. Ground return for $AV_{DD3,3}$ and $AV_{DD1,8}$.
16	REFIO	Reference I/O. Output of the internal 1.2V precision bandgap reference. Bypass with a 0.1µF capacitor to AGND. REFIO can be driven with an external reference source.
17	FSADJ	Full-Scale Current Adjustment. Connect an external resistor R_{SET} between FSADJ and DACREF to set the output full-scale current. The output full-scale current is equal to 32 x V_{REF} / R_{SET} .
18	DACREF	Current-Set Resistor Return Path. Internally connected to ground, but do not use as ground connection.
19, 34, 35	AV _{DD1.8}	Analog Supply Voltage. Accepts a 1.71V to 1.89V supply voltage range. Bypass with a 0.1 μ F capacitor to AGND.
28	OUTN	Complementary DAC Output. Negative terminal for current output.
29	OUTP	DAC Output. Positive terminal for current output.
36, 41	AV _{CLK} Clock Supply Voltage. Accepts a 3.135V to 3.465V supply voltage range. E 0.1μF capacitor to CGND.	
37, 40	CGND	Clock Supply Ground
38	CLKN	Complementary Converter Clock Input. Negative input terminal for differential converter clock.
39	CLKP	Converter Clock Input. Positive input terminal for differential converter clock.
45, 47, 49, 51, 53, 55, 57, 59, 62, 64, 66, 68	D11P, D10P, D9P, D8P, D7P, D6P, D5P, D4P, D3P, D2P, D1P, D0P	Differential Positive LVDS Inputs. Data bits D0–D11 (offset binary format).
61	DV _{DD1.8}	Digital Supply Voltage. Accepts a 1.71V to 1.89V supply voltage range. Bypass with a 0.1µF capacitor to DGND.
_	EP	Exposed Pad. Must be connected to common point for AGND, DGND, and CGND through a low-impedance path. EP is internally connected to AGND, DGND, and CGND.



Pin Description

Detailed Description

Architecture

The MAX5889 high-performance, 12-bit, current-steering DAC (see the Functional Diagram) operates with DAC update rates up to 600Msps. The current-steering array generates differential full-scale currents in the 2mA to 20mA range. An internal current-switching network, in combination with external 50 Ω termination resistors, converts the differential output currents into a differential output voltage with a 0.1V to 1V peak-topeak output voltage range. The analog outputs have a -1.0V to +1.1V voltage compliance. For applications requiring high dynamic performance, use the differential output configuration and limit the output voltage swing to ±0.5V at each output. An integrated 1.2V bandgap reference, control amplifier, and user-selectable external resistor determine the data converter's full-scale output range.

Reference Architecture and Operation

The MAX5889 operates with the internal 1.2V bandgap reference or an external reference voltage source. REFIO serves as the input for an external, low-impedance reference source or as a reference output when the DAC operates in internal reference mode. For stable operation with the internal reference, bypass REFIO to AGND with a 0.1 μ F capacitor. The REFIO output resistance is 10k Ω . Buffer REFIO with a high-input-impedance amplifier when using it as a reference source for external circuitry.

The MAX5889's reference circuit (Figure 1) employs a control amplifier to regulate the full-scale current, IOUTFS, for the differential current outputs of the DAC. Calculate the output current as follows:

$$I_{OUTFS} = 32 \times \frac{V_{REFIO}}{R_{SET}} \times \left(1 - \frac{1}{2^{12}}\right)$$

where I_{OUTFS} is the full-scale output current of the DAC. R_{SET} (located between FSADJ and DACREF) determines the amplifier's full-scale output current for the DAC. See Table 1 for a matrix of different I_{OUTFS} and R_{SET} selections.

Table 1. IOUTFS and RSET Selection MatrixBased on a Typical 1.200V ReferenceVoltage

FULL-SCALE CURRENT	R _{SET} (kΩ)				
IOUTFS (mA)	CALCULATED	1% EIA STD			
2	19.2	19.1			
5	7.68	7.5			
10	3.84	3.83			
15	2.56	2.55			
20	1.92	1.91			

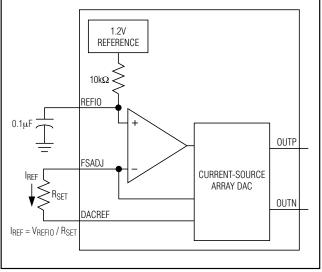


Figure 1. Reference Architecture, Internal Reference Configuration

Analog Outputs (OUTP, OUTN)

The complementary current outputs (OUTP, OUTN) can be connected in a single-ended or differential configuration. A load resistor converts these two output currents into complementary single-ended output voltages. A transformer or a differential amplifier converts the differential voltage existing between OUTP and OUTN to a single-ended voltage. When not using a transformer, terminate each output with a 25 Ω resistor to ground and a 50 Ω resistor between the outputs.

To generate a single-ended output, select OUTP as the output and connect OUTN to AGND. Figure 2 shows a simplified diagram of the internal output structure of the MAX5889.

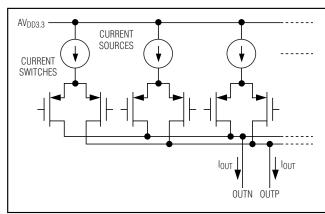


Figure 2. Simplified Analog Output Structure

Clock Inputs (CLKP, CLKN)

To achieve the best possible jitter performance, the MAX5889 features flexible differential clock inputs (CLKP, CLKN) that operate from a separate clock power supply (AV_{CLK}). Drive the differential clock inputs from a single-ended or a differential clock source. For highest dynamic performance, differential clock source is required. For single-ended operation, drive CLKP and bypass CLKN to CGND.

CLKP and CLKN are internally biased at AV_{CLK} / 2, allowing the AC-coupling of clock sources directly to the device without external resistors to define the DC level. The input resistance from CLKP and CLKN to ground is approximately $5k\Omega$.

Data-Timing Relationship

Figure 3 shows the timing relationship between digital LVDS data, clock, and output signals. The MAX5889 features a 2ns hold, a -1.2ns setup, and a 2.5ns propagation delay time. There is a 5.5 clock-cycle latency between data write operation and the corresponding analog output transition.

LVDS Data Inputs

The MAX5889 has 12 pairs of LVDS data inputs (offset binary format) and can accept data rates up to 600MWps. Each differential input pair is terminated with an internal 110Ω resistor. The common-mode input resistance is $3.2k\Omega$.

Power-Down Operation (PD)

The MAX5889 features a power-down mode that reduces the DAC's power consumption. Set PD high to power down the MAX5889. Set PD low or leave unconnected for normal operation.

When powered down, the MAX5889 overall power consumption is reduced to less than 13μ W. The MAX5889 requires 350µs to wake up from power-down and enter a fully operational state if the external reference is used. If the internal reference is used, the power-down recovery time is 10ms. The PD internal pulldown circuit sets the MAX5889 in normal mode when PD is left unconnected.

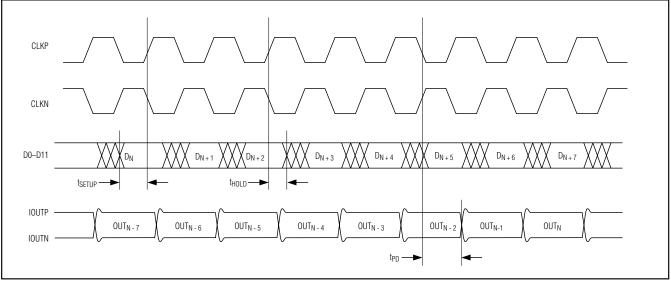


Figure 3. Timing Relationship Between Clock, Input Data, and Analog Output



Applications Information

Clock Interface

To achieve the best possible jitter performance, the MAX5889 features flexible differential clock inputs (CLKP, CLKN) that operate from a separate clock power supply (AV_{CLK}). Use a low-jitter clock to reduce the DAC's phase noise and wideband noise. To achieve the best DAC dynamic performance, the CLKP/CLKN input source must be designed carefully. The differential clock (CLKN and CLKP) input can be driven from a single-ended or a differential clock source. Use differential clock drive to achieve the best dynamic performance from the DAC. For single-ended operation, drive CLKP with a low-noise source and bypass CLKN to CGND with a 0.1μ F capacitor.

Figure 4 shows a convenient and quick way of applying a differential signal created from a single-ended source using a wideband transformer. Alternatively, drive CLKP/CLKN from a CMOS-compatible clock source. Use sine wave or AC-coupled differential ECL/PECL drive for best dynamic performance.

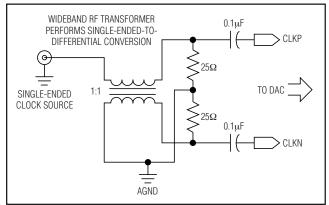


Figure 4. Differential Clock-Signal Generation

Differential Output Coupling Using a Wideband RF Transformer

Use a pair of transformers (Figure 5) or a differential amplifier configuration to convert the differential voltage existing between OUTP and OUTN to a single-ended voltage. Optimize the dynamic performance by using a differential transformer-coupled output and limit the output power to <0dBm full scale. To achieve the best dynamic performance, use the differential transformer configuration. Terminate the DAC as shown in Figure 5, and use 50Ω termination at the transformer singleended output. This provides double 50Ω termination for the DAC output network. With the double-terminated output and 20mA full-scale current, the DAC produces a full-scale signal level of approximately -2dBm. Pay close attention to the transformer core saturation characteristics when selecting a transformer for the MAX5889. Transformer core saturation can introduce strong 2ndorder harmonic distortion especially at low output frequencies and high signal amplitudes. For best results, connect the center tap of the transformer to ground. When not using a transformer, terminate each DAC output to ground with a 25Ω resistor. Additionally, place a 50Ω resistor between the outputs (Figure 6).

For a single-ended unipolar output, select OUTP as the output and connect OUTN to AGND. Operating the MAX5889 single-ended is not recommended because it degrades the dynamic performance.

The distortion performance of the DAC depends on the load impedance. The MAX5889 is optimized for 50Ω differential double termination. Using higher termination impedance degrades distortion performance and increases output noise voltage.

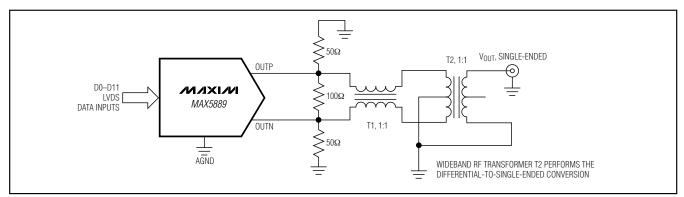


Figure 5. Differential-to-Single-Ended Conversion Using a Wideband RF Transformer

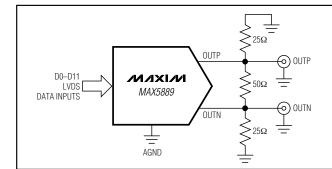


Figure 6. Differential Output Configuration

Grounding, Bypassing, and Power-Supply Considerations

Grounding and power-supply decoupling strongly influence the MAX5889 performance. Unwanted digital crosstalk coupling through the input, reference, power supply, and ground connections affects dynamic performance. High-speed, high-frequency applications require closely followed proper grounding and powersupply decoupling. These techniques reduce EMI and internal crosstalk that can significantly affect the MAX5889 dynamic performance.

Use a multilayer printed circuit (PC) board with separate ground and power-supply planes. Run high-speed signals on lines directly above the ground plane. Keep digital signals as far away from sensitive analog inputs and outputs, reference input sense lines, commonmode inputs, and clock inputs as practical. Use a symmetric design of clock input and the analog output lines to minimize 2nd-order harmonic distortion components, thus optimizing the DAC's dynamic performance. Keep digital signal paths short and run lengths matched to avoid propagation delay and data skew mismatches.

The MAX5889 requires five separate power-supply inputs for analog (AV_{DD1.8} and AV_{DD3.3}), digital (DV_{DD1.8} and DV_{DD3.3}), and clock (AV_{CLK}) circuitry. Decouple each AV_{DD3.3}, AV_{DD1.8}, AV_{CLK}, DV_{DD3.3}, and DV_{DD1.8} input with a separate 0.1µF capacitor as close to the device as possible with the shortest possible connection to the respective ground plane (Figure 7). Connect all the 3.3V supplies together at one point with ferrite beads to minimize supply noise coupling. Decouple all five power-supply voltages at the point they enter the PC board with tantalum or electrolytic capacitors. Ferrite beads with additional decoupling capacitors forming a pi network can also improve performance. Similarly, connect all 1.8V supplies together at one point with ferrite beads. The analog and digital power-supply inputs AV_{DD3.3}, AV_{CLK}, and DV_{DD3.3} allow a 3.135V to 3.465V supply voltage range. The analog and digital power-supply inputs AV_{DD1.8} and DV_{DD1.8} allow a 1.71V to 1.89V supply voltage range.

The MAX5889 is packaged in a 68-pin QFN-EP package with exposed paddle, providing optimized DAC AC performance. The exposed pad must be soldered to the ground plane of the PC board. Thermal efficiency is not the key factor, since the MAX5889 features lowpower operation. The exposed pad ensures a solid ground connection between the DAC and the PC board's ground layer.

The data converter die attaches to an EP lead frame with the back of this frame exposed at the package bottom surface, facing the PC board side of the package. This allows for a solid attachment of the package to the PC board with standard infrared (IR) reflow soldering techniques. A specially created land pattern on the PC board, matching the size of the EP (6mm x 6mm), ensures the proper attachment and grounding of the DAC. Place vias into the land area and implement

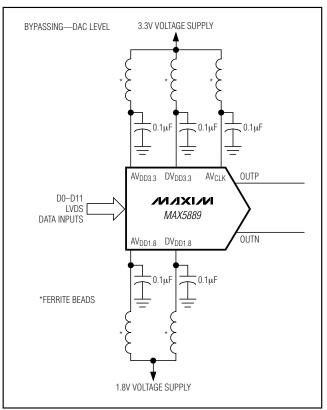


Figure 7. Recommended Power-Supply Decoupling and Bypassing Circuitry



large ground planes in the PC board design to ensure the highest dynamic performance of the DAC. Connect the MAX5889 exposed paddle to the common connection point of DGND, AGND, and CGND. Vias connect the top land pattern to internal or external copper planes. Use as many vias as possible to the ground plane to minimize inductance. The vias should have a diameter greater than 0.3mm.

Static Performance Parameter Definitions

Integral Nonlinearity (INL)

Integral nonlinearity is the deviation of the values on an actual transfer function from a line drawn between the end points of the transfer function, once offset and gain errors have been nullified. For a DAC, the deviations are measured at every individual step.

Differential Nonlinearity (DNL)

Differential nonlinearity is the difference between an actual step height and the ideal value of 1 LSB.

Offset Error

The offset error is the difference between the ideal and the actual offset current. For a DAC, the offset point is the average value at the output for the two midscale digital input codes with respect to the full scale of the DAC. This error affects all codes by the same amount.

Gain Error

A gain error is the difference between the ideal and the actual full-scale output voltage on the transfer curve, after nullifying the offset error. This error alters the slope of the transfer function and corresponds to the same percentage error in each step.

Settling Time

The settling time is the amount of time required from the start of a transition until the DAC output settles its new output value to within the converter's specified accuracy.

Glitch Impulse

A glitch is generated when a DAC switches between two codes. The largest glitch is usually generated around the midscale transition, when the input pattern transitions from 011...111 to 100...000. The glitch impulse is found by integrating the voltage of the glitch at the midscale transition over time. The glitch impulse is usually specified in pV•s.

Dynamic Performance Parameter Definitions

Signal-to-Noise Ratio (SNR)

For a waveform perfectly reconstructed from digital samples, the theoretical maximum SNR is the ratio of the full-scale analog output (RMS value) to the RMS quantization error (residual error). The ideal, theoretical maximum can be derived from the DAC's resolution (N bits):

$$SNR = 6.02 \times N + 1.76$$

However, noise sources such as thermal noise, reference noise, clock jitter, etc., affect the ideal reading; therefore, SNR is computed by taking the ratio of the RMS signal to the RMS noise, which includes all spectral components minus the fundamental, the first four harmonics, and the DC offset.

Noise Spectral Density

The DAC output noise floor is the sum of the quantization noise and the output amplifier noise (thermal and shot noise). Noise spectral density is the noise power in 1Hz bandwidth, specified in dBFS/Hz.

Spurious-Free Dynamic Range (SFDR)

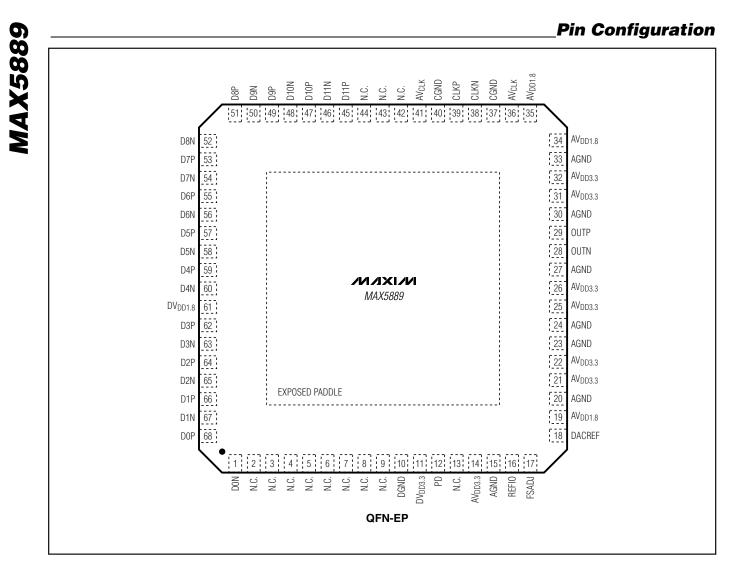
SFDR is the ratio of RMS amplitude of the carrier frequency (maximum signal components) to the RMS value of their next-largest distortion component. SFDR is usually measured in dBc and with respect to the carrier frequency amplitude or in dBFS with respect to the DAC's full-scale range. Depending on its test condition, SFDR is observed within a predefined window or to Nyquist.

Two-Tone Intermodulation Distortion (IMD)

The two-tone IMD is the ratio expressed in dBc (or dBFS) of the worst 3rd-order IMD differential product to either output tone. The two-tone IMD performance of the MAX5889 is tested with the two individual output tone levels set to at least -6.5dBFS.

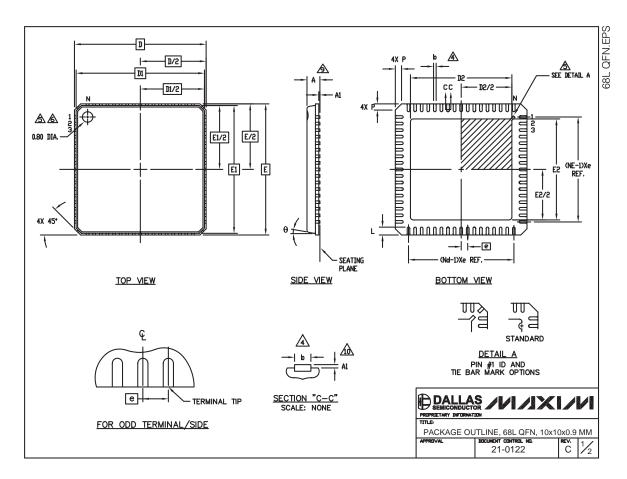
Adjacent Channel Leakage Power Ratio (ACLR)

Commonly used in combination with wideband codedivision multiple-access (WCDMA), ACLR reflects the leakage power ratio in dB between the measured power within a channel relative to its adjacent channel. ACLR provides a quantifiable method of determining out-of-band spectral energy and its influence on an adjacent channel when a bandwidth-limited RF signal passes through a nonlinear device.



Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)

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A1	0.00	0.01	0.0	-	11		Nd IS THE NUMBER OF TERMINALS IN X-DIRECTION &
b	0.18	0.23	0.3	0	4	•	Ne IS THE NUMBER OF TERMINALS IN Y-DIRECTION.
D		10.00 BSC)			<u> </u>	λ DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
D1		9.75 BSC)			~	0.20 AND 0.25mm FROM TERMINAL TIP.
e		0.50 BSC)			∠5.	THE PIN #1 IDENTIFIER MUST BE LOCATED ON THE TOP SURFACE OF
Ε		10.00 BSC)				THE PACKAGE BY USING INDENTATION MARK OR OTHER FEATURE
E1		9.75 BSC)				OF PACKAGE BODY. DETAILS OF PIN #1 IDENTIFIER IS OPTIONAL, BUT MUST
L	0.50	0.60	0.6	5		Â	BE LOCATED WITHIN ZONE INDICATED.
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Nd		17			3		3. PACKAGE WARPAGE MAX 0.10mm.
Ne		17			3		APPLIES TO EXPOSED SURFACE OF PADS AND TERMINALS
θ	0		12"			7	
Р	0	0.42	0.6	0		11	1. MEETS JEDEC MD-220.
			D2			E2	
	G CODE 5800-2	MIN 7.55	NDM 7.70	MAX 7.85	MIN 7.55	N⊡M 7.70	MAX 7.85
	5800-2 5800-4	5.65	5.80	5.95	5.65	5.80	5.95

Revision History

Pages changed at Rev 1: 1-7, 9, 12, 13, 15, 16

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